Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN42G30EF BK083LM is a 30% glass reinforced, high performance polyamide resin, biobased, developed for electrical and electronics applications and well suited for laser marking. It is also a PPA resin.

Product information

Resin Identification	PA-GF30	ISO 1043
Part Marking Code	>PA-GF30<	ISO 11469
Part Marking Code	>PPA-GF30<	SAE J1344
ISO designation	ISO 16396-PA,GF30,M1CGHO2R, S10-100	

Rheological properties

	dry/cond.		
Molding shrinkage, parallel	0.5 / -	%	ISO 294-4, 2577
Molding shrinkage, normal	0.9 / -	%	ISO 294-4, 2577

Typical mechanical properties

	dry/cond.		
Tensile modulus	1.39E6 / 1.36E6	psi	ISO 527-1/-2
Tensile stress at break, 5mm/min	24900 / 21300	psi	ISO 527-1/-2
Tensile strain at break, 5mm/min	2.7 / 2.5	%	ISO 527-1/-2
Flexural modulus	1.31E6 / 1.29E6	psi	ISO 178
Flexural strength	37400 / 32300	psi	ISO 178
Charpy impact strength, 23°C	42.3 / 32.8	ftlb/in²	ISO 179/1eU
Charpy impact strength, -30°C	27.6 / 27.6	ftlb/in²	ISO 179/1eU
Charpy notched impact strength, 23°C	6.18 / 5.23	ftlb/in²	ISO 179/1eA
Charpy notched impact strength, -30°C	4.76 / 4.76	ftlb/in²	ISO 179/1eA

Thermal properties

	dry/cond.		
Melting temperature, 10°C/min	597 / *	°F	ISO 11357-1/-3
Melting temperature, first heat	603 / *	°F	ISO 11357-1/-3
Glass transition temperature, 10°C/min	185 / -	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	531 / *	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.11 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel, -40-23°C	0.111 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel, 55-160°C	0.0778 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.417 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal, -40-23°C	0.367 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal, 55-160°C	0.528 / *	E-4/°F	ISO 11359-1/-2

Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

Flammability

	dry/cond.		
Burning Behav. at thickness h	HB / *	class	IEC 60695-11-10
Thickness tested	0.0315 / *	in	IEC 60695-11-10
FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	0.984	in/min	ISO 3795 (FMVSS 302)

Electrical properties

	dry/cond.		
Volume resistivity	>1E13 / -	Ohm.m	IEC 62631-3-1
Comparative tracking index	600 / -		IEC 60112
Dielectric Constant, 1 GHz	3.5 / -		ASTM D 2520 B
Dielectric Constant, 23 °C, 10 GHz	3.5 / -		ASTM D 2520 B / IPC-TM-650
Dissipation Factor, 1 GHz	116 / -	E-4	ASTM D 2520 B
Dissipation Factor, 23 °C, 10 GHz	102 / -	E-4	ASTM D 2520 B / IPC-TM-650

Physical/Other properties

	dry/cond.		
Humidity absorption, 2mm	1.2 / *	%	Sim. to ISO 62
Water absorption, 2mm	3.1 / *	%	Sim. to ISO 62
Water absorption, Immersion 24h	0.3 / *	%	Sim. to ISO 62
Density	0.0487 / -	lb/in³	ISO 1183

Injection

Drying Recommended	yes	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	6 - 8	h
Processing Moisture Content	≤0.1	%
Melt Temperature Optimum	626	°F
Min. melt temperature	626	°F
Max. melt temperature	635	°F
Min. mold temperature	230	°F
Max. mold temperature	266	°F
Hold Pressure Time (h is the max. wall thickness of the part in mm)	h^2+2	s

Characteristics

Processing	Injection Molding
Additives	Release agent
Special characteristics	Heat stabilized or stable to heat, Laser Markable

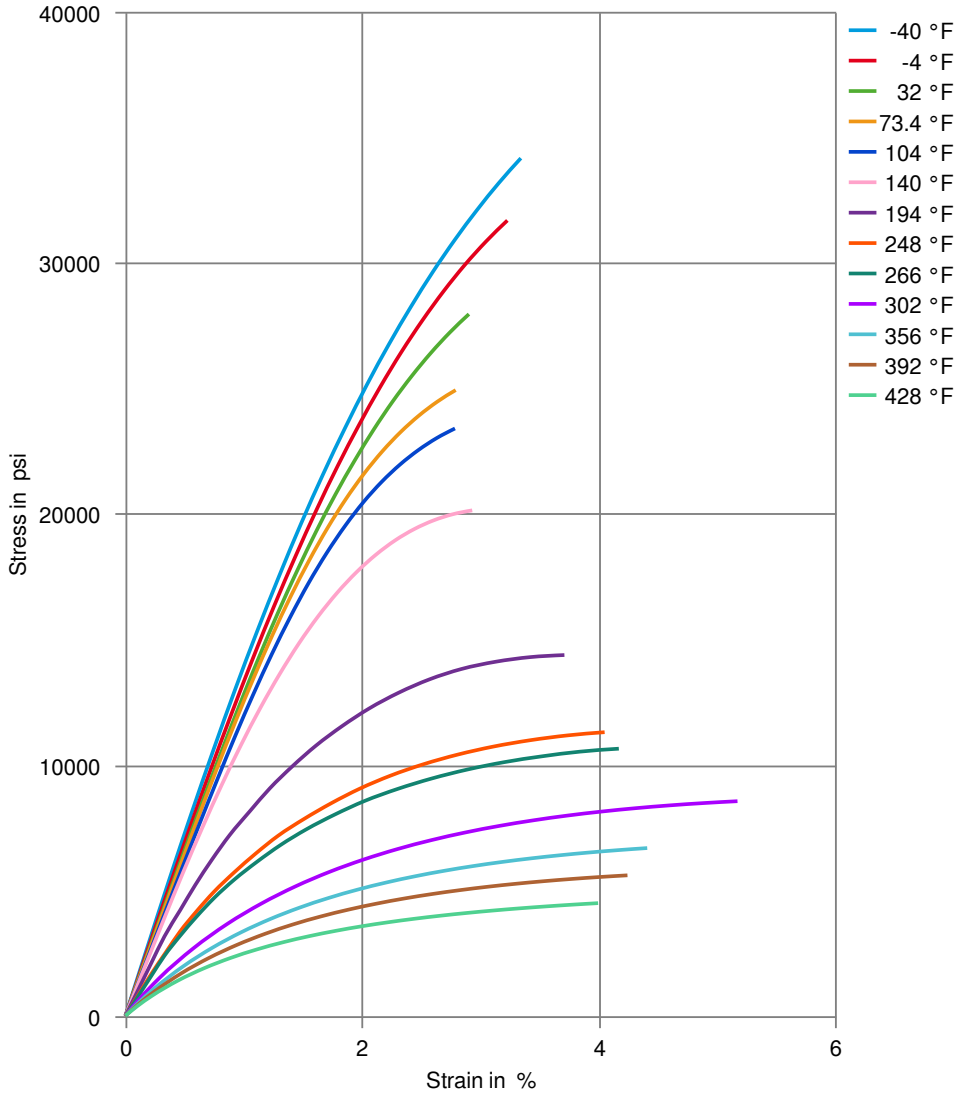
Additional information

Injection molding	For molding machine components, use corrosion resistant and wear resistant steel. For details please contact our representative. Limit the residence time of the resin in the machine. Use proper protective equipment and adequate ventilation.

Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

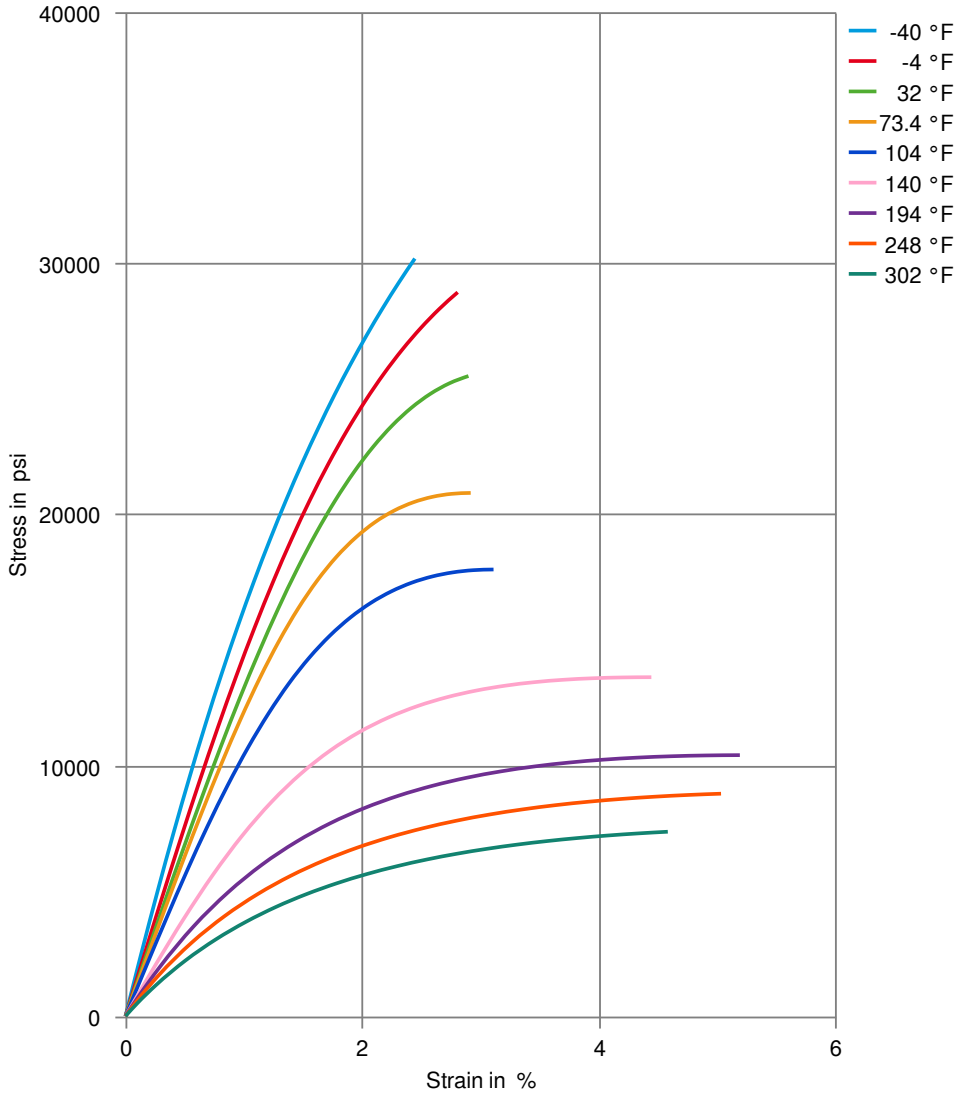
Stress-strain (dry)



Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

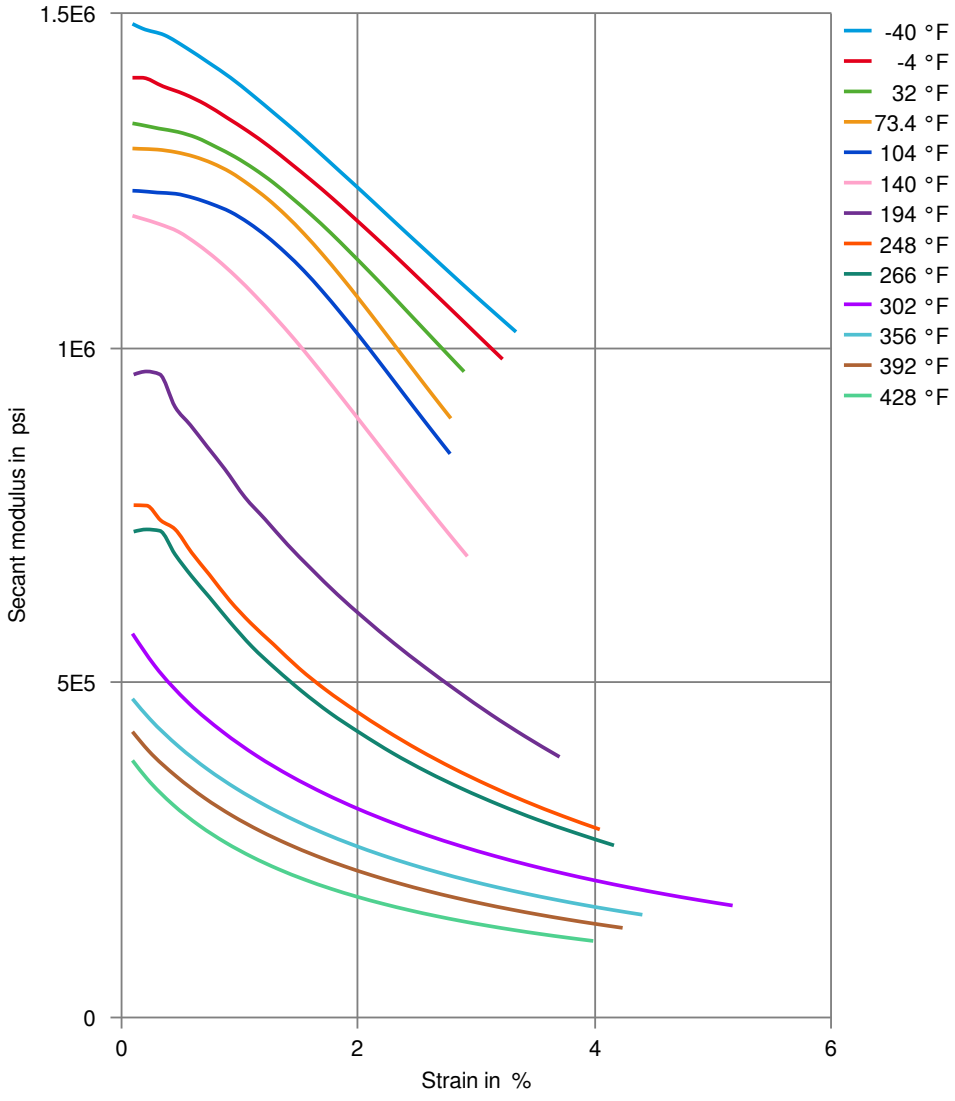
Stress-strain (cond.)



Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

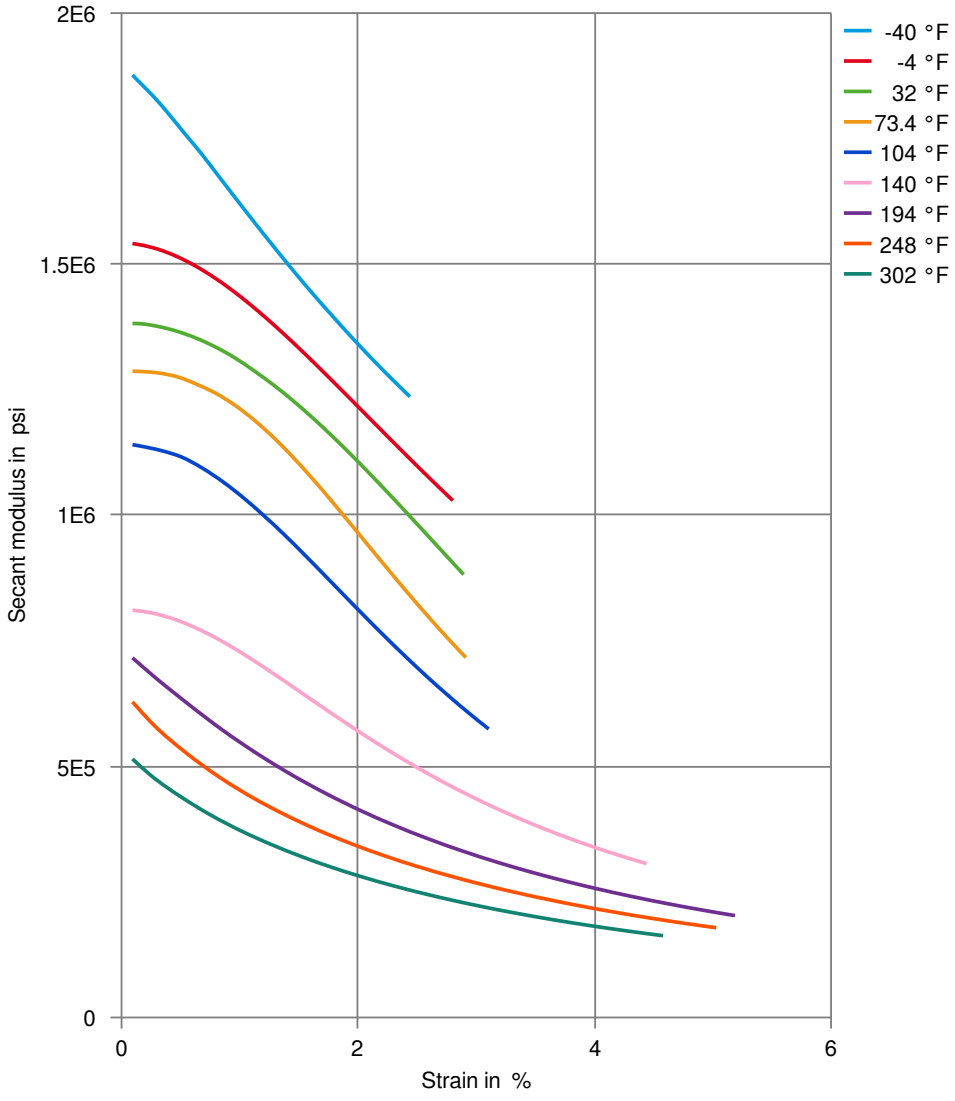
Secant modulus-strain (dry)



Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

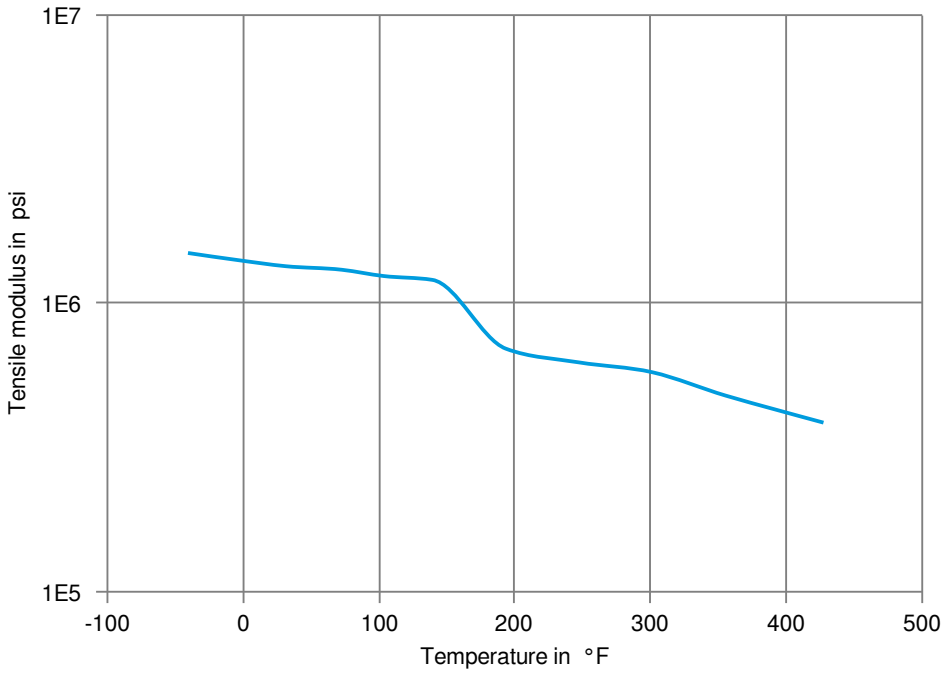
Secant modulus-strain (cond.)



Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

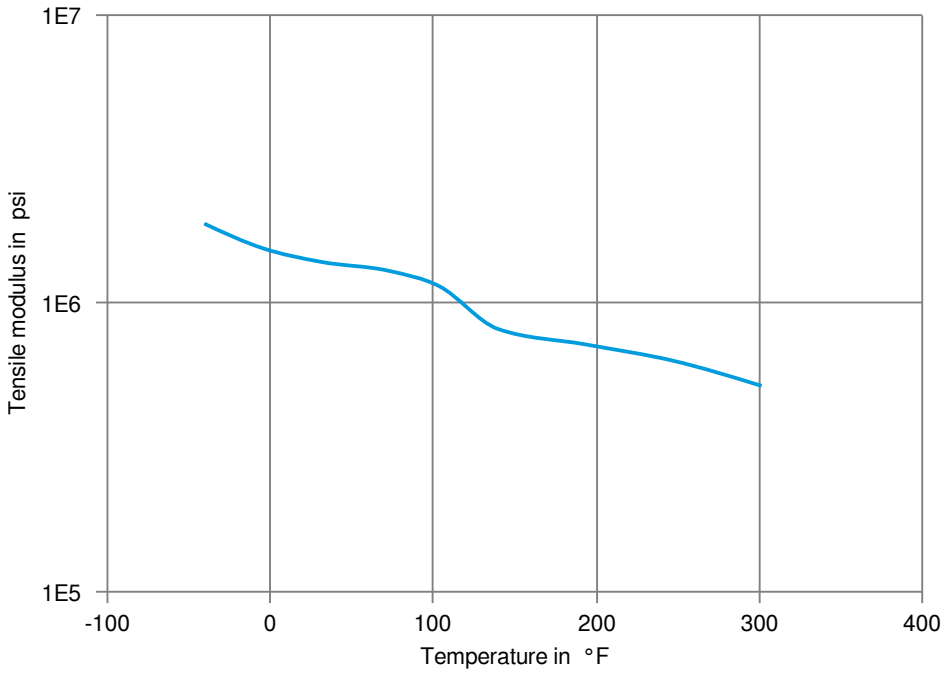
Tensile modulus-temperature (dry)



Zytel® HTN42G30EF BK083LM

HIGH PERFORMANCE POLYAMIDE RESIN

Tensile modulus-temperature (cond.)



Revised: 2026-08-12 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colorants or other additives may cause significant variations in data values. Properties of molded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material mentioned in this publication should satisfy themselves that they can meet all applicable safety and health standards. We strongly recommend that users seek and adhere to the manufacturer's current instructions for handling each material they use, and entrust the handling of such material to adequately trained personnel only. Please call the telephone numbers listed for additional technical information. Call Customer Services for the appropriate Materials Safety Data Sheets (MSDS) before attempting to process our products.
Copyright © 2026 Celanese or its affiliates. All rights reserved.
Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates.